

# DSA7U01

## Silicon PNP epitaxial planar type

For Low-frequency amplifier

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

### ■ Marking Symbol: 4H

### ■ Packaging

DSA7U01×0L Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-100	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-100	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V
Collector current	$I_C$	-0.5	A
Peak collector current	$I_{CP}$	-1	A
Collector power dissipation *1	$P_C$	1	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Operating ambient temperature	$T_{opr}$	-40 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*1: Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

Absolute maximum rating without heat sink for  $P_C$  is 0.5 W

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -100 \mu\text{A}, I_B = 0$	-100			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Forward current transfer ratio *1	$h_{FE1}$ *2	$V_{CE} = -10 \text{ V}, I_C = -150 \text{ mA}$	90		220	—
	$h_{FE2}$	$V_{CE} = -5 \text{ V}, I_C = -500 \text{ mA}$	50			
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		-0.2	-0.6	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		-0.9	-1.2	V
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_C = -50 \text{ mA}$		120		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			30	pF

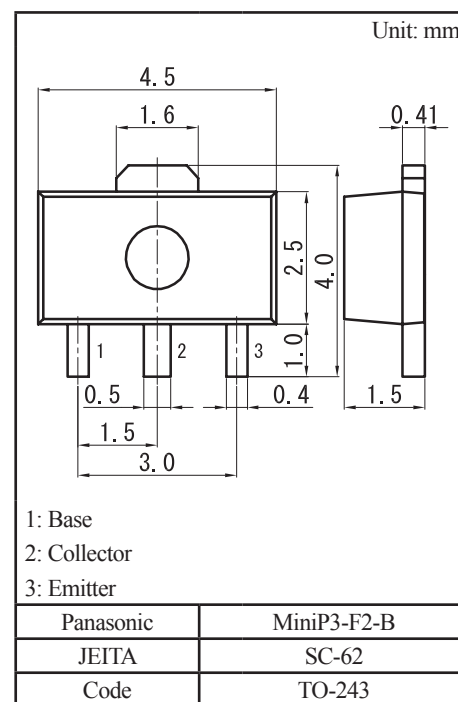
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

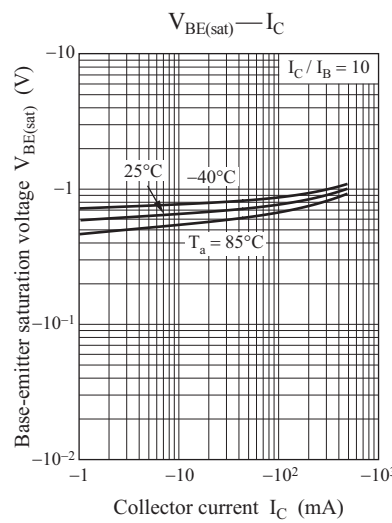
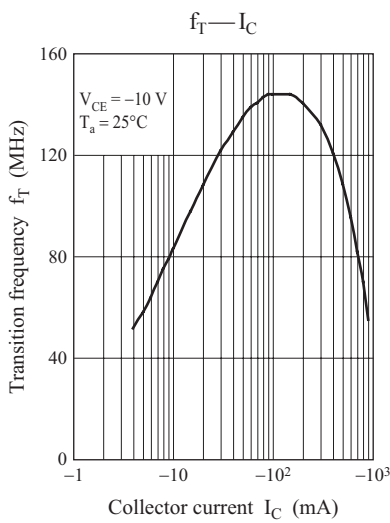
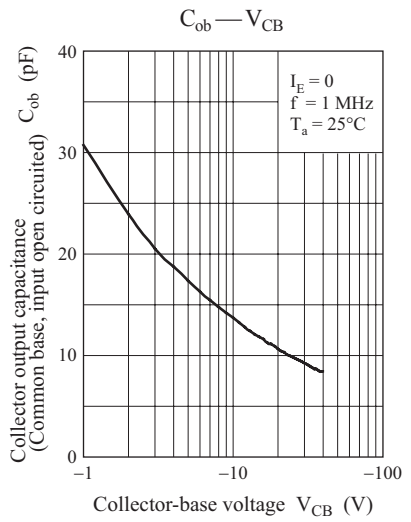
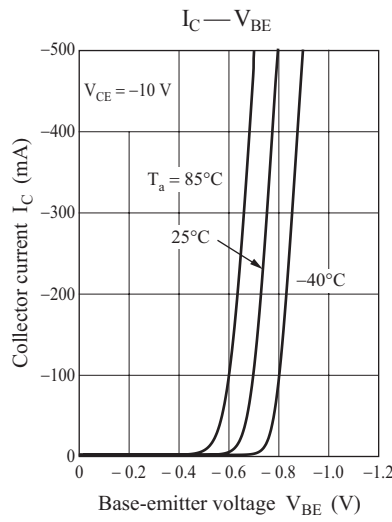
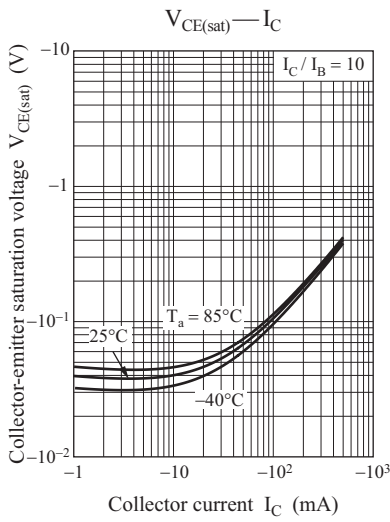
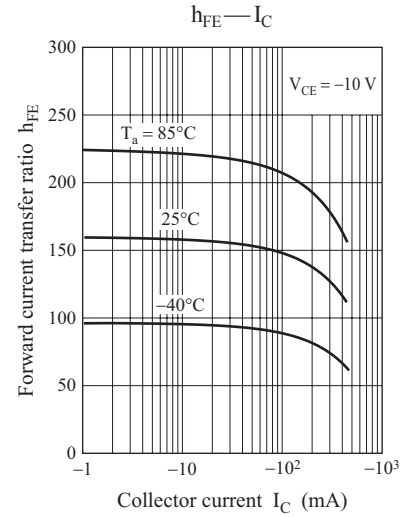
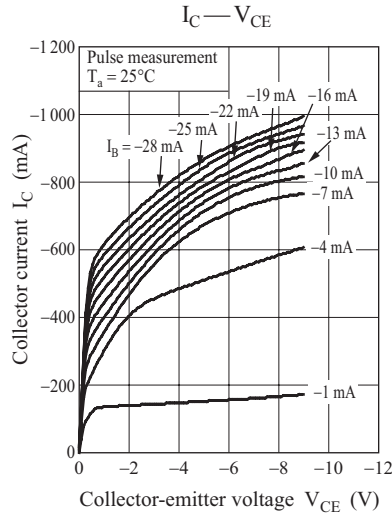
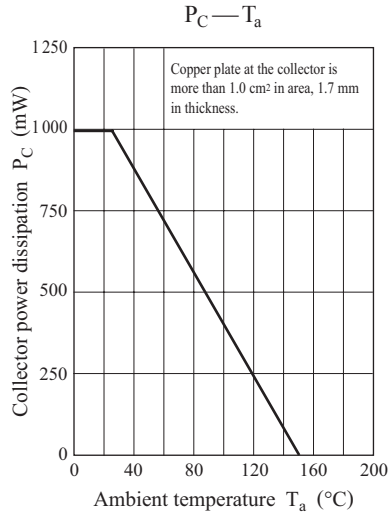
2. \*1: Pulse measurement

\*2: Rank classification

Code	Q	R	0
Rank	Q	R	No-rank
$h_{FE1}$	90 to 155	130 to 220	90 to 220
Marking Symbol	4HQ	4HR	4H

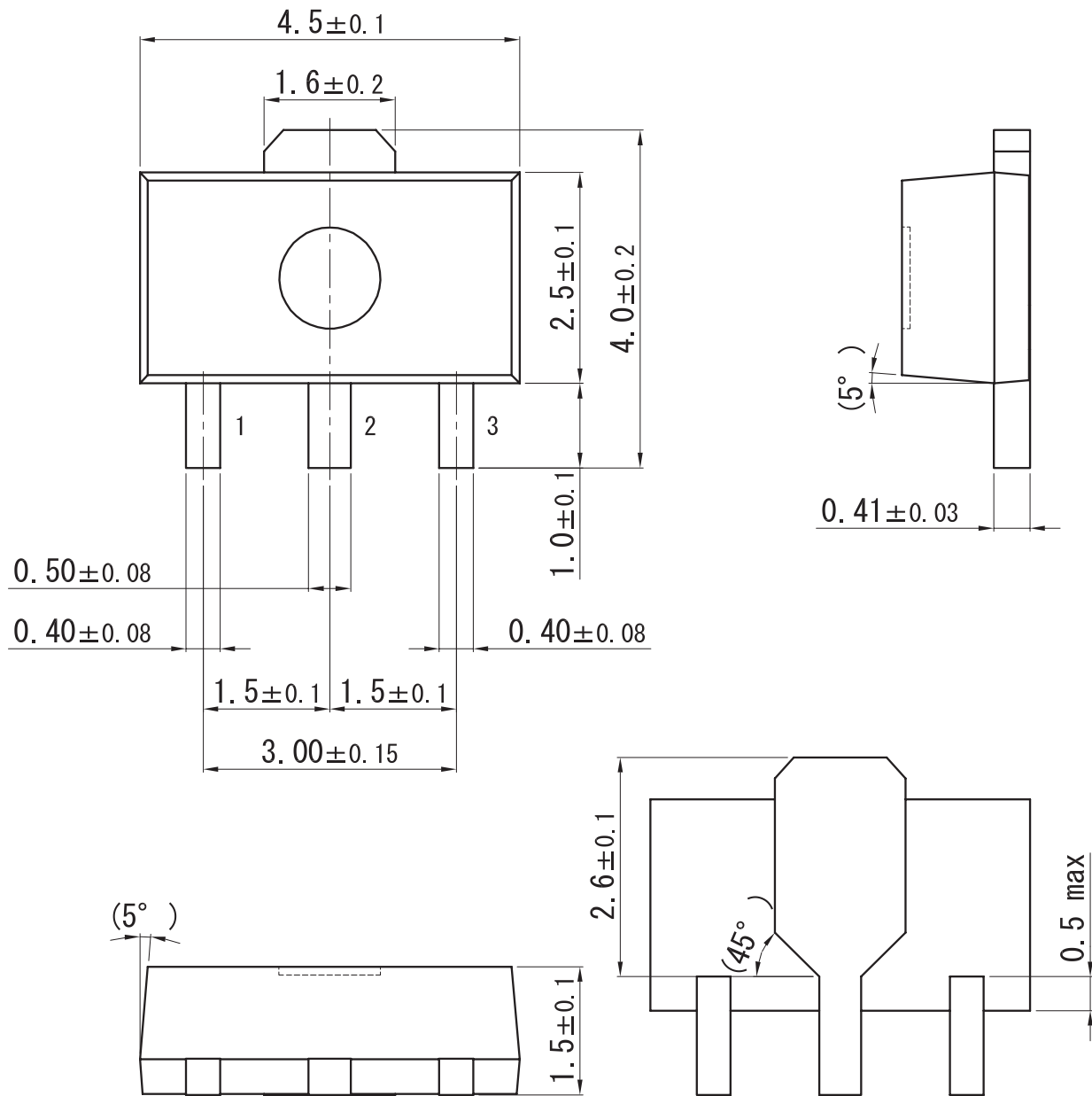
Product of no-rank is not classified and have no marking symbol for rank.



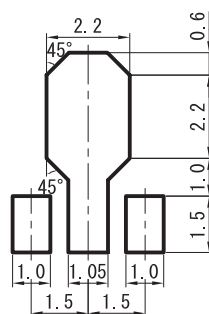


MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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